

ABSTRACT OF THE DISCLOSURE

A semiconductor device is retained on a retaining section. A mask is set on the semiconductor device and has an opening at which part of the semiconductor device is exposed. An extruding section is moved by a first drive section over an opening in the mask and, during this movement, extrudes a fluidizing resin into the opening in the mask. A squeegee is moved by a second drive section over the opening in the mask to allow a movement of the fluidizing resin present over the opening which is extruded into the opening from an extruding section and a removal of any excessive resin from the plane of the opening.

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